

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	17	"5923089"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L2	5	"6737356"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L3	0	"6737356" and residue	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L4	171	"5614055"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38

L5	109	("MEM" or micromachine or microelectromechanical) and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L6	14	("20020001873" "5610431" "5895233" "6140144" "6214644" "6316840" "6384473").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L7	2	"6528344" and ultrasonic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L8	554	(IC) and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L9	118	(IC) and microelectronic and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38

L10	24	(IC) and microelectromechanical and package and ultrasonic adj bond \$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L11	0	lid with wiring same sealing same operating adj space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L12	164	lid with wiring same sealing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L13	2	lid with wiring same sealing same MEM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L14	957	lid same sealing same MEM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38

L15	3	lid same sealing same MEM same wiring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L16	109	("MEM" or micromachine or microelectromechanical) and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L17	40	L16 and lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L18	21	L16 and lid and wiring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L19	61	"6384473"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38

L20	21	L18 and ultrasonic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L21	21741072	US "20040016995"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L22	2	"20040016995"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L23	1	"20040016995" and ultrasonic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L24	18	"6579751"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38

L25	21741129	L1 L2 L3 L4 L5 L6 L7 L8 L9 L10 L11 L12 L13 L14 L15 L16 L17 L18 L19 L20 L21 L22 L23 L24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:38
L26	3616	257/678.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:40
L27	1584	257/704.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:40
L28	783	257/684.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:41
L29	3791	Higashi.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:41

L30	54	29 and MEM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:42
L31	13	30 and lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/20 15:42
S1	4708	"TFT" and ("GOLD" or gate with overlap\$4 with "LDD")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:46
S2	4708	"TFT" and ("GOLD" or (gate with overlap\$4 with "LDD"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 07:59
S3	2018	S2 and pixel and ("p" adj (type or channel)) and ("n" adj (type or channel))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:01

S4	1097	S3 and pixel adj TFT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:01
S5	870	S4 and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:01
S6	736	S5 and organic adj resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:01
S7	569	S6 and (LDD with overlap\$4 with gate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:30
S8	338	S7 and light adj shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:02

S9	45	S8 and anodic adj oxidat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:03
S10	45	S9 and (gate with (insulat\$4 or dielectric))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:03
S11	11	("5247190" "5399502" "5594569" "5643826" "5923962" "5998841" "6046479" "6166397" "6166414" "6172671" "6180982").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/21 08:30
S12	0	S11 and (LDD with overlap\$4 with gate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:30
S13	4708	"TFT" and ("GOLD" or (gate with overlap\$4 with "LDD"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:30

S14	2018	S13 and pixel and ("p" adj (type or channel)) and ("n" adj (type or channel))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:30
S15	1097	S14 and pixel adj TFT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:30
S16	870	S15 and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:30
S17	736	S16 and organic adj resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:30
S18	569	S17 and (LDD with overlap\$4 with gate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:36

S19	338	S18 and light adj shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:31
S20	338	S19 and pixel adj TFT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:31
S21	310	S20 and p adj channel adj TFT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:31
S22	51	S21 and P adj channel with overlap \$4 with LDD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 08:32
S23	7	("5292675" "5323042" "5643826" "5923962" "6166397" "6166414" "6259120").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/21 08:33
S24	7	("5292675" "5323042" "5643826" "5923962" "6166397" "6166414" "6259120").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/21 08:36

S25	24	("5292675" "5323042" "5643826" "5923962" "6091115" "6096581" "6166397" "6166414" "6198133" "6218678" "6259120" "6281552" "6346730" "6362507" "6380007" "6410368" "6420988" "6461899" "6469317" "6492681" "6498369" "6506636" "6563482" "6580475").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/21 08:36
S26	13	S25 and (LDD with overlap\$4 with gate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 10:00
S27	2	"6380007" and anodic adj oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 10:04
S28	9	"6380007" and oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 10:01

S39	0	"6737356" and residue	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 13:17
S40	145	"5614055"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:15
S41	75	("MEM" or micromachine or microelectromechanical) and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:48
S42	14	("20020001873" "5610431" "5895233" "6140144" "6214644" "6316840" "6384473").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:26
S43	0	"6528344" and ultrasonic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:26

S44	402	(IC) and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:27
S45	90	(IC) and microelectronic and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:27
S46	22	(IC) and microelectromechanical and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:28
S47	0	lid with wiring same sealing same operating adj space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:47
S48	149	lid with wiring same sealing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:47

S49	2	lid with wiring same sealing same MEM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:48
S50	938	lid same sealing same MEM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:48
S51	3	lid same sealing same MEM same wiring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:48
S52	97	("MEM" or micromachine or microelectromechanical) and package and ultrasonic adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:49
S53	38	S52 and lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:49

S54	21	S52 and lid and wiring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:56
S55	60	"6384473"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:53
S56	21	S54 and ultrasonic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:59
S57	20092793	US "20040016995"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:59
S58	2	"20040016995"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:59

S59	1	"20040016995" and ultrasonic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 20:59
S60	22	"6579751"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/14 21:39

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